



Product Change Notification / CENO-11PPSC306

Date:

11-Mar-2024

Product Category:

High Voltage Power Modules

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6870 Final Notice: Qualification of INFG as an additional fabrication site for selected APTGTQ100xx, APTGTQ200xx, APTGTQ150TA65TPG, APTGTQ50H65T3G, APTGTQ50TA65T3G, APTGTQ50VDA65T3G, CMMIGTQ100TA65T3NM and MSCGTQ100HD65C1AG device families available in 650V Bare Die Products.

Affected CPNs:

[CENO-11PPSC306_Affected_CPN_03112024.pdf](#)

[CENO-11PPSC306_Affected_CPN_03112024.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of INFG as an additional fabrication site for selected APTGTQ100xx, APTGTQ200xx, APTGTQ150TA65TPG, APTGTQ50H65T3G, APTGTQ50TA65T3G, APTGTQ50VDA65T3G, CMMIGTQ100TA65T3NM and MSCGTQ100HD65C1AG device families available in 650V Bare Die Products.

Pre and Post Change Summary:

	Pre Change	Post Change	
Fabrication Site	Infineon Technologies Austria AG (INFA)	Infineon Technologies Austria AG (INFA)	Infineon Technologies Germany (INFG)
Wafer Diameter	8 Inches	8 Inches	12 Inches
Certification	ISO-9001 / IATF16949	ISO-9001 / IATF16949	ISO-9001

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying INFG as an additional fabrication site.

Change Implementation Status:In Progress

Estimated First Ship Date:May 1, 2024 (date code: 2418)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2024					>	May 2024				
Workweek	10	11	12	13	14		18	19	2	21	22
Qual Report Availability		x									
Final PCN Issue Date		x									
Estimated Implementation Date							x				

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:March 11, 2024: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_CENO-11PPSC306_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

- MSCGTQ100HD65C1AG
- CMMIGTQ100TA65T3NM
- APTGTQ50H65T3G
- APTGTQ200A65T3G
- APTGTQ200DA65T3G
- APTGTQ100H65T3G
- APTGTQ100DDA65T3G
- APTGTQ100SK65T1G
- APTGTQ150TA65TPG
- APTGTQ50VDA65T3G
- APTGTQ50TA65T3G
- APTGTQ200SK65T3G
- APTGTQ100A65T1G
- APTGTQ100DA65T1G